

Discription

The HSC1205-01ETG protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



DFN1006-2L (SOD-882)

Features

- ★ Low Leakage
- ★ Response Time is Typically < 1 ns
- ★ ESD Rating of Class 3 per Human Body Model
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ These are Pb-Free Devices
- ★ We declare that the material of product compliance with RoHS requirements and Halogen Free.



Circuit Diagram

Ordering Information

Product ID	Pack	Qty(PCS)
HSC1205-01ETG	DFN1006-2L(SOD-882)	10000

Absolute Ratings(Tamb = 25°C)

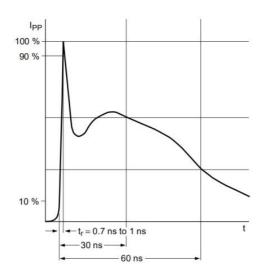
Symbol	Parameter		Value	Units
P _{PP}	Peak Pulse Power (t₂ = 8/20µs)		90	W
TL	Maximum lead temperature for soldering during 10s		260	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
T _{op}	Operating Temperature Range		-40 to +125	°C
Tj	Maximum junction temperature		150	°C
	IEC61000-4-2 (ESD) air discha contact dischar		±30 ±30	KV



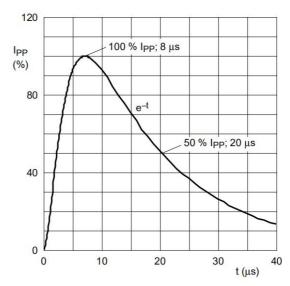
Electrical Characteristics

Symbol	Parameter	Test Condition	Min	Тур	Max	Units
Vrwm	Reverse Working Voltage				5.0	V
V_{BR}	Reverse Breakdown Voltage	I _T = 1mA	5.8		8.2	V
IR	Reverse Leakage Current	V _{RWM} = 5.0V			100	nA
Vc	Clamping Voltage	$I_{PP} = 9A, t_P = 8/20 \mu s$			10	V
С	Junction Capacitance	V _R = 0V, f = 1MHz		15	20	pF

Typical Characteristics

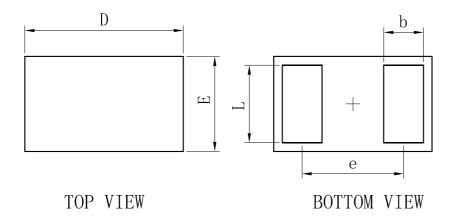


IEC61000-4-2 Waveform

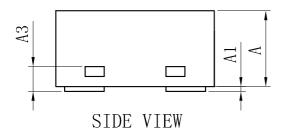


IEC 61000-4-5 Waveform(8/20µs pulse)

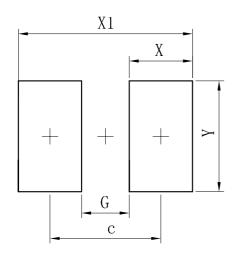
Outline and Dimensions



DFN1006-2L(SOD-882)			
Dim	Min	Тур	Max
D	0. 95	1.00	1.05
Е	0. 55	0.60	0.65
е	_	0.64	_
L	0.44	0.49	0. 54
b	0.20	0. 25	0.30
A	0. 43	0.48	0. 53
A1	0	1	0.05
A3	0. 127REF.		
All Dimensions in mm			



Soldering Footprint



Dimensions	(mm)
С	0.70
G	0.30
X	0.40
X1	1. 10
Y	0.70

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